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Sheet 1 of 1

Form 1449*

INFORMATION DISCLOSURE STATEMENT
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Applicant: Leonard Forbes et al.

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**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
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JKL | Zirinsky, S., et al., "Electrical Resistivity of Amorphous Silicon Resistor Films", Extended Abstracts of the Spring Meeting of the Electrochemical Society, Washington, DC, pp. 147-149, (1971)

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*Substitute Disclosure Statement Form (PTO-1449)

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